

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Rui Huang	12/05/2008
Heap Hoe Kuan	12/05/2008
Yaojian Lin	12/05/2008
Seng Guan Chow	12/05/2008
<b>RECEIVING PARTY DATA</b>	
Name:	STATS ChipPAC, Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	12332253
<b>CORRESPONDENCE DATA</b>	
Fax Number:	(602)264-2743
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	602-748-4408
Email:	main@patentgroupaz.com
Correspondent Name:	Robert D. Atkins
Address Line 1:	605 W. Knox Road
Address Line 2:	Suite 104
Address Line 4:	Tempe, ARIZONA 85284
ATTORNEY DOCKET NUMBER:	2515.0148
NAME OF SUBMITTER:	Robert D. Atkins

CH \$40.00 12332253

Total Attachments: 4  
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source=Assignments#page3.tif  
source=Assignments#page4.tif

ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, RUI HUANG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING AN IPD BENEATH A SEMICONDUCTOR DIE WITH DIRECT CONNECTION TO EXTERNAL DEVICES, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0148, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

  
\_\_\_\_\_  
Signature for RUI HUANG

Witnessed on this date:

5 Dec 2008  
\_\_\_\_\_

Signature of Witness:

  
\_\_\_\_\_

Printed Name of Witness:

GOH HIN HUA  
\_\_\_\_\_

Address of Witness:

5 YISHUN STREET 23  
S'PORE 768442  
\_\_\_\_\_

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HEAP HOE KUAN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING AN IPD BENEATH A SEMICONDUCTOR DIE WITH DIRECT CONNECTION TO EXTERNAL DEVICES, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0148, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for HEAP HOE KUAN

Witnessed on this date:

5 Dec 2008

Signature of Witness:



Printed Name of Witness:

GOH HIN HWA

Address of Witness:

5 YISHUN STREET 23  
S'PORE 768442

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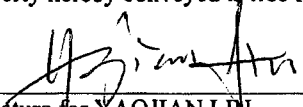
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING AN IPD BENEATH A SEMICONDUCTOR DIE WITH DIRECT CONNECTION TO EXTERNAL DEVICES, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0148, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for YAOJIAN LIN Dec. 5, 2008

Witnessed on this date: 5 Dec 2008

Signature of Witness: 

Printed Name of Witness: GOH HIN HUA

Address of Witness: 5 YISHUN STREET 23  
S'PORE 768442

ASSIGNMENT AND AGREEMENT

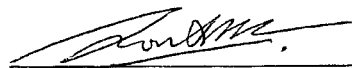
For good and valuable consideration, the receipt of which is hereby acknowledged, I, SENG GUAN CHOW of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING AN IPD BENEATH A SEMICONDUCTOR DIE WITH DIRECT CONNECTION TO EXTERNAL DEVICES, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0148, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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\_\_\_\_\_  
Signature for SENG GUAN CHOW

Witnessed on this date: 5 Dec 2008

Signature of Witness: 

Printed Name of Witness: GOH HIN HWA

Address of Witness: 5 YISHUN STREET 23  
S'PORE 768442